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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c712-04e-p

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

PIC16C712/716

Key Features PIC [®] Mid-Range Reference Manual (DS33023)	PIC16C712	PIC16C716
Operating Frequency	DC – 20 MHz	DC – 20 MHz
Resets (and Delays)	POR, BOR (PWRT, OST)	POR, BOR (PWRT, OST)
Program Memory (14-bit words)	1K	2К
Data Memory (bytes)	128	128
Interrupts	7	7
I/O Ports	Ports A,B	Ports A,B
Timers	3	3
Capture/Compare/PWM modules	1	1
8-bit Analog-to-Digital Module	4 input channels	4 input channels

PIC16C7XX FAMILY OF DEVICES

		PIC16C710	PIC16C71	PIC16C711	PIC16C712	PIC16C715	PIC16C716	PIC16C72A	PIC16C73B
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20	20	20
Memory	EPROM Program Memory (x14 words)	512	1K	1K	1K	2K	2K	2K	4K
	Data Memory (bytes)	36	36	68	128	128	128	128	192
	Timer Module(s)	TMR0	TMR0	TMR0	TMR0 TMR1 TMR2	TMR0	TMR0 TMR1 TMR2	TMR0 TMR1 TMR2	TMR0 TMR1 TMR2
Peripherals	Capture/Compare/ PWM Module(s)	—	—	—	1	—	1	1	2
	Serial Port(s) (SPI™/I ² C™, USART)	—	—	—	—	—	—	SPI/I ² C	SPI/I ² C, USART
	A/D Converter (8-bit) Channels	4	4	4	4	4	4	5	5
	Interrupt Sources	4	4	4	7	4	7	8	11
	I/O Pins	13	13	13	13	13	13	22	22
	Voltage Range (Volts)	2.5-6.0	3.0-6.0	2.5-6.0	2.5-5.5	2.5-5.5	2.5-5.5	2.5-5.5	2.5-5.5
Features	In-Circuit Serial Programming™	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	_	Yes	Yes	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC

PIC16C712/716

NOTES:

2.0 MEMORY ORGANIZATION

There are two memory blocks in each of these PIC[®] microcontroller devices. Each block (Program Memory and Data Memory) has its own bus so that concurrent access can occur.

Additional information on device memory may be found in the $PIC^{\mbox{\tiny R}}$ Mid-Range Reference Manual, (DS33023).

2.1 Program Memory Organization

The PIC16C712/716 has a 13-bit Program Counter (PC) capable of addressing an 8K x 14 program memory space. PIC16C712 has 1K x 14 words of program memory and PIC16C716 has 2K x 14 words of program memory. Accessing a location above the physically implemented address will cause a wraparound.

The Reset vector is at 0000h and the interrupt vector is at 0004h.





FIGURE 2-2: PROGRAM MEMORY MAP AND STACK OF PIC16C716



2.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and Peripheral Modules for controlling the desired operation of the device. These registers are implemented as static RAM. A list of these registers is give in Table 2-1. The Special Function Registers can be classified into two sets; core (CPU) and peripheral. Those registers associated with the core functions are described in detail in this section. Those related to the operation of the peripheral features are described in detail in that peripheral feature section.

TABLE 2-1. SPECIAL FUNCTION REGISTER SUMMARY	TABLE 2-1:	SPECIAL FUNCTION REGISTER SUMMARY
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Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets (4)
Bank 0											
00h	INDF ⁽¹⁾	Addressing	this location	uses conten	ts of FSR to ac	ldress data r	nemory (not	a physical re	gister)	0000 0000	0000 0000
01h	TMR0	Timer0 Mod	lule's Registe	er						xxxx xxxx	uuuu uuuu
02h	PCL ⁽¹⁾	Program Co	ounter's (PC)	Least Signif	icant Byte					0000 0000	0000 0000
03h	STATUS ⁽¹⁾	IRP ⁽⁴⁾	RP1 ⁽⁴⁾	RP0	TO	PD	Z	DC	С	rr01 1xxx	rr0q quuu
04h	FSR ⁽¹⁾	Indirect Dat	a Memory Ad	dress Pointe	er					xxxx xxxx	uuuu uuuu
05h	PORTA ^(5,6)	—	_	(7)	PORTA Data	Latch when	written: POR	TA pins whe	n read	xx xxxx	xu uuuu
06h	PORTB ^(5,6)	PORTB Dat	ta Latch whe	n written: PC	RTB pins whe	n read				xxxx xxxx	uuuu uuuu
07h	DATACCP	(7)	(7)	(7)	(7)	(7)	DCCP	(7)	DT1CK	xxxx xxxx	xxxx xuxu
08h-09h	_	Unimpleme	Unimplemented							-	-
0Ah	PCLATH ^(1,2)	—	—	_	Write Buffer fo	or the upper	5 bits of the I	Program Cou	inter	0 0000	0 0000
0Bh	INTCON ⁽¹⁾	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	_	_	—	CCP1IF	TMR2IF	TMR1IF	-0 0000	-0 0000
0Dh	_	Unimpleme	nted							-	-
0Eh	TMR1L	Holding Re	gister for the	Least Signifi	cant Byte of th	e 16-bit TMF	1 Register			xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Re	gister for the	Most Signific	cant Byte of the	e 16-bit TMR	1 Register			xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	00 0000	uu uuuu
11h	TMR2	Timer2 Mod	lule's Registe	er						0000 0000	0000 0000
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h-14h											
15h	CCPR1L	Capture/Co	mpare/PWM	Register1 (L	SB)					xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Co	mpare/PWM	Register1 (N	/ISB)					xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000
18h-1Dh	—	Unimpleme	nted							-	-
1Eh	ADRES	A/D Result	Register							xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	_	ADON	0000 00-0	0000 00-0

Legend: x = unknown, u = unchanged, q = value depends on condition, --- = unimplemented, read as '0',

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for PC<12:8> whose contents are transferred to the upper byte of the program counter.

3: Other (non Power-up) Resets include: external Reset through MCLR and the Watchdog Timer Reset.

4: The IRP and RP1 bits are reserved. Always maintain these bits clear.

5: On any device Reset, these pins are configured as inputs.

6: This is the value that will be in the port output latch.

7: Reserved bits; Do Not Use.

PIC16C712/716

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets (4)
INDF ⁽¹⁾	Addressing	this location	uses conten	ts of FSR to ac	ddress data r	memory (not	a physical re	gister)	0000 0000	0000 0000
OPTION_ REG	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
PCL ⁽¹⁾	Program Co	ounter's (PC)	Least Signi	ficant Byte					0000 0000	0000 0000
STATUS ⁽¹⁾	IRP ⁽⁴⁾	RP1 ⁽⁴⁾	RP0	TO	PD	Z	DC	С	rr01 1xxx	rr0q quuu
FSR ⁽¹⁾	Indirect Dat	a Memory A	ddress Point	er					xxxx xxxx	uuuu uuuu
TRISA	—	—	_(7)	PORTA Data	Direction Re	gister			x1 1111	x1 1111
TRISB	PORTB Dat	ta Direction F	Register						1111 1111	1111 1111
TRISCCP	(7)	(7)	(7)	(7)	(7)	TCCP	(7)	TT1CK	xxxx x1x1	xxxx x1x1
—	Unimpleme	nted							-	-
PCLATH ^(1,2)	_	—	_	Write Buffer fo	or the upper	5 bits of the I	Program Cou	unter	0 0000	0 0000
INTCON ⁽¹⁾	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
PIE1	_	ADIE	—	-	—	CCP1IE	TMR2IE	TMR1IE	-0000	-0000
_	Unimpleme	nted							-	-
PCON	—	—	—	_	—	—	POR	BOR	dd	uu
—	Unimpleme	Unimplemented							-	-
PR2	Timer2 Peri	Timer2 Period Register							1111 1111	1111 1111
_	Unimpleme	nted							-	-
ADCON1	—	—	—	-	—	PCFG2	PCFG1	PCFG0	000	000
	Name INDF ⁽¹⁾ OPTION_ REG PCL ⁽¹⁾ STATUS ⁽¹⁾ FSR ⁽¹⁾ TRISA TRISCCP PCLATH ^(1,2) INTCON ⁽¹⁾ PIE1 PCON PCON PR2 ADCON1	NameBit 7INDF ⁽¹⁾ AddressingOPTION- REGRBPUPCL(¹⁾ Program CoSTATUS ⁽¹⁾ IRP ⁽⁴⁾ FSR ⁽¹⁾ Indirect DatTRISAORTB DatTRISCCPORTB DatPCLATH ^(1,2) ORPCLATH ^(1,2) ORPCLATH ^(1,2) ORPCLATH ^(1,2) ORPCLATH ^(1,2) ORPCLATH ^(1,2) ORPCONORPCONInmplemePCQTimer2 PeriPR2Timer2 PeriADCON1ON	NameBit 7Bit 6INDF ⁽¹⁾ Addressingtrial locationOPTION_ REGRBPUINTEDGPCL ⁽¹⁾ RDGramINTEDGSTATUS ⁽¹⁾ IRP ⁽⁴⁾ RP1 ⁽⁴⁾ FSR ⁽¹⁾ INdirect DataRP1 ⁽⁴⁾ TRISAIndirect DataTRISAORTB DataIndirect DataTRISCCP(7)-(7)PCLATH ^(1,2) Indirect DataPCLATH ^(1,2) ADIEPIE1ADIEPCONIndirect DataIndirect DataPCONIndirect DataIndirect DataPR2Timer2 Pet-RegisterPR2Inimplemet-Indirect DataInimplemet-ADCON1Inimplemet-	NameBit 7Bit 6Bit 5INDF ⁽¹⁾ Addressing this location the sconterOPTION_ REGRBPUINTEDGTOCSPCL ⁽¹⁾ Program C-tre's (PC) teast SigniSTATUS ⁽¹⁾ IRP ⁽⁴⁾ RP1 ⁽⁴⁾ RP0STATUS ⁽¹⁾ IRP ⁽⁴⁾ RP1 ⁽⁴⁾ RP0FSR ⁽¹⁾ Indirect Data Memory Attress PointTRISA-I-PCLATHPORTB Data Terction registerTRISCCP-I-OUINIPLEUNIMPLEIPCLATH ^(1,2) -I-INTCON ⁽¹⁾ GIEPEIETOIEPIE1-ADIE-PCONII-PCONII-PR2Timer2 PetEregisterPR2Timer2 PetEregisterPCON1I-ADCON1-II-II-II-II-II-II </td <td>NameBit 7Bit 6Bit 5Bit 4INDF⁽¹⁾Addressing to callState to callState to callOPTION- REGRBPUINTEDGTOCSTOSEPCL⁽¹⁾RPGTOCSTOSESTATUS⁽¹⁾IRP⁽⁴⁾RP14RP0TOSTATUS⁽¹⁾IRP⁽⁴⁾RP14RP0TOFSR⁽¹⁾INdirect Data</td> <td>NameBit 7Bit 6Bit 5Bit 4Bit 3INDF⁽¹⁾Addressing control of PSR to addressing control of PSRTOCSTOSEPSAOPTION_RBPUINTEDGTOCSTOSEPSAOPTION_RBPUINTEDGTOCSTOSEPSAPCL⁽¹⁾Program C-uter's (PC - test Significant BytePSASTATUS⁽¹⁾IRP⁽⁴⁾RP1RP0TOPDFSR⁽¹⁾Indirect Data Memory Address PointrePORTA Data Direction RegisterTRISAPOPORTB Data Direction registerPOTRISCCPPOOPOPCLATH^(1,2)PCLATH^(1,2)OOOOPOINTCON⁽¹⁾GIEPEIEINTEINTERBIEPIE1-ADIEOPCON-OPCONPCONPCONPCONPCONPCON<t< td=""><td>NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2INDF(1)Addressing International Strest Contractional Strest Contract Contract Contract Contract Contract Contractional Strest Cont</td><td>NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1INDF(1)Addressing Lange ControlSocialS</td><td>NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1Bit 0INDF(1)Addressive conversion of the second conversion of the s</td><td>NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1Bit 0Value on: POR, BORINDF(1)Addressing EvanceSit 1Sit 1<td< td=""></td<></td></t<></td>	NameBit 7Bit 6Bit 5Bit 4INDF ⁽¹⁾ Addressing to callState to callState to callOPTION- REGRBPUINTEDGTOCSTOSEPCL ⁽¹⁾ RPGTOCSTOSESTATUS ⁽¹⁾ IRP ⁽⁴⁾ RP14RP0TOSTATUS ⁽¹⁾ IRP ⁽⁴⁾ RP14RP0TOFSR ⁽¹⁾ INdirect Data	NameBit 7Bit 6Bit 5Bit 4Bit 3INDF ⁽¹⁾ Addressing control of PSR to addressing control of PSRTOCSTOSEPSAOPTION_RBPUINTEDGTOCSTOSEPSAOPTION_RBPUINTEDGTOCSTOSEPSAPCL ⁽¹⁾ Program C-uter's (PC - test Significant BytePSASTATUS ⁽¹⁾ IRP ⁽⁴⁾ RP1RP0TOPDFSR ⁽¹⁾ Indirect Data Memory Address PointrePORTA Data Direction RegisterTRISAPOPORTB Data Direction registerPOTRISCCPPOOPOPCLATH ^(1,2) PCLATH ^(1,2) OOOOPOINTCON ⁽¹⁾ GIEPEIEINTEINTERBIEPIE1-ADIEOPCON-OPCONPCONPCONPCONPCONPCON <t< td=""><td>NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2INDF(1)Addressing International Strest Contractional Strest Contract Contract Contract Contract Contract Contractional Strest Cont</td><td>NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1INDF(1)Addressing Lange ControlSocialS</td><td>NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1Bit 0INDF(1)Addressive conversion of the second conversion of the s</td><td>NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1Bit 0Value on: POR, BORINDF(1)Addressing EvanceSit 1Sit 1<td< td=""></td<></td></t<>	NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2INDF(1)Addressing International Strest Contractional Strest Contract Contract Contract Contract Contract Contractional Strest Cont	NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1INDF(1)Addressing Lange ControlSocialS	NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1Bit 0INDF(1)Addressive conversion of the second conversion of the s	NameBit 7Bit 6Bit 5Bit 4Bit 3Bit 2Bit 1Bit 0Value on: POR, BORINDF(1)Addressing EvanceSit 1Sit 1 <td< td=""></td<>

TABLE 2-1: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Legend: x = unknown, u = unchanged, q = value depends on condition, — = unimplemented, read as '0',

Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.

2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for PC<12:8> whose contents are transferred to the upper byte of the program counter.

3: Other (non Power-up) Resets include: external Reset through MCLR and the Watchdog Timer Reset.

4: The IRP and RP1 bits are reserved. Always maintain these bits clear.

5: On any device Reset, these pins are configured as inputs.

6: This is the value that will be in the port output latch.

7: Reserved bits; Do Not Use.

2.2.2.3 INTCON Register

The INTCON Register is a readable and writable register which contains various enable and flag bits for the TMR0 register overflow, RB Port change and External RB0/INT pin interrupts. **Note:** Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 2-6: INTCON REGISTER (ADDRESS 0Bh, 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x			
GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	R	= Readable bit	
bit7	·						bit0	W U -n	 Writable bit Unimplemented bit, read as '0' Value at POR Reset 	
bit 7:	7: GIE: Global Interrupt Enable bit 1 = Enables all unmasked interrupts 0 = Disables all interrupts									
bit 6:	 6: PEIE: Peripheral Interrupt Enable bit 1 = Enables all unmasked peripheral interrupts 0 = Disables all peripheral interrupts 									
bit 5:	TOIE : TMR0 Overflow Interrupt Enable bit 1 = Enables the TMR0 interrupt 0 = Disables the TMR0 interrupt									
bit 4:	IINTE: RB0/INT External Interrupt Enable bit 1 = Enables the RB0/INT external interrupt 0 = Disables the RB0/INT external interrupt									
bit 3:	RBIE : RB Port Change Interrupt Enable bit 1 = Enables the RB port change interrupt 0 = Disables the RB port change interrupt									
bit 2:	T0IF : TMR0 Overflow Interrupt Flag bit 1 = TMR0 register has overflowed (must be cleared in software) 0 = TMR0 register did not overflow									
bit 1:	INTF: RB0/INT External Interrupt Flag bit 1 = The RB0/INT external interrupt occurred (must be cleared in software) 0 = The RB0/INT external interrupt did not occur									
bit 0:	 RBIF: RB Port Change Interrupt Flag bit 1 = At least one of the RB7:RB4 pins changed state (must be cleared in software) 0 = None of the RB7:RB4 pins have changed state 									

4.0 **TIMER0 MODULE**

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- · Internal or external clock select
- Edge select for external clock
- 8-bit software programmable prescaler
- · Interrupt on overflow from FFh to 00h

Figure 4-1 is a simplified block diagram of the Timer0 module.

Additional information on timer modules is available in the PIC[®] Mid-Range Reference Manual, (DS33023).

4.1 **Timer0** Operation

Timer0 can operate as a timer or as a counter.

Timer mode is selected by clearing bit T0CS (OPTION_REG<5>). In timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If the TMR0 register is written, the increment is inhibited for the following two instruction cycles. The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting bit T0CS (OPTION_REG<5>). In Counter mode, Timer0 will increment on every rising or falling edge of pin RA4/ T0CKI. The incrementing edge is determined by the Edge Select Timer0 Source bit TOSE (OPTION_REG<4>). Clearing bit T0SE selects the rising edge. Restrictions on the external clock input are discussed below.

When an external clock input is used for Timer0, it must meet certain requirements. The requirements ensure the external clock can be synchronized with the internal phase clock (Tosc). Also, there is a delay in the actual incrementing of Timer0 after synchronization.

Additional information on external clock requirements is available in the PIC[®] Mid-Range Reference Manual, (DS33023).

4.2 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module or as a postscaler for the Watchdog Timer, respectively (Figure 4-2). For simplicity, this counter is being referred to as "prescaler" throughout this data sheet. Note that there is only one prescaler available, which is mutually exclusively shared between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer and vice-versa.

The prescaler is not readable or writable.

The PSA and PS2:PS0 bits (OPTION_REG<3:0>) determine the prescaler assignment and prescale ratio.

Clearing bit PSA will assign the prescaler to the Timer0 module. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4, ..., 1:256 are selectable.

Setting bit PSA will assign the prescaler to the Watchdog Timer (WDT). When the prescaler is assigned to the WDT, prescale values of 1:1, 1:2, ..., 1:128 are selectable.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., CLRF 1, MOVWF 1, BSF 1, x....etc.) will clear the prescaler. When assigned to WDT, a CLRWDT instruction will clear the prescaler along with the WDT.

Note: Writing to TMR0 when the prescaler is assigned to Timer0 will clear the prescaler count, but will not change the prescaler assignment.



FIGURE 4-1: TIMER0 BLOCK DIAGRAM

6.0 TIMER2 MODULE

The Timer2 module timer has the following features:

- 8-bit timer (TMR2 register)
- 8-bit period register (PR2)
- Readable and writable (both registers)
- Software programmable prescaler (1:1, 1:4, 1:16)
- Software programmable postscaler (1:1 to 1:16)
- Interrupt on TMR2 match of PR2

Timer2 has a control register, shown in Figure 6-1. Timer2 can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption.

Figure 6-2 is a simplified block diagram of the Timer2 module.

Additional information on timer modules is available in the PIC[®] Mid-Range Reference Manual, (DS33023).

FIGURE 6-1: T2CON: TIMER2 CONTROL REGISTER (ADDRESS 12h)



FIGURE 6-2: TIMER2 BLOCK DIAGRAM



7.1 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin RB3/CCP1. An event is defined as:

- every falling edge
- every rising edge
- every 4th rising edge
- every 16th rising edge

An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

FIGURE 7-3:

CAPTURE MODE OPERATION BLOCK DIAGRAM



7.1.1 CCP PIN CONFIGURATION

In Capture mode, the CCP output must be disabled by setting the TRISCCP<2> bit.

Note: If the RB3/CCP1 is configured as an output by clearing the TRISCCP<2> bit, a write to the DCCP bit can cause a capture condition.

7.1.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work.

7.1.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit CCP1IE (PIE1<2>) clear to avoid false interrupts and should clear the flag bit CCP1IF following any such change in Operating mode.

7.1.4 CCP PRESCALER

There are four prescaler settings, specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any Reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore the first capture may be from a non-zero prescaler. Example 7-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the "false" interrupt.

EXAMPLE 7-1: CHANGING BETWEEN CAPTURE PRESCALERS

CLRF	CCP1CON	;Turn CCP module off
MOVLW	NEW_CAPT_PS	;Load the W reg with
		; the new prescaler
		; mode value and CCP ON
MOVWF	CCP1CON	;Load CCP1CON with this
		; value

8.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) Converter module has four inputs.

The A/D allows conversion of an analog input signal to a corresponding 8-bit digital number (refer to Application Note AN546 for use of A/D Converter). The output of the sample and hold is the input into the converter, which generates the result via successive approximation. The analog reference voltage is software selectable to either the device's positive supply voltage (VDD) or the voltage level on the RA3/AN3/VREF pin.

The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator. Additional information on the A/D module is available in the PIC[®] Mid-Range Reference Manual, (DS33023).

The A/D module has three registers. These registers are:

- A/D Result Register (ADRES)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off, and any conversion is aborted.

The ADCON0 register, shown in Figure 8-1, controls the operation of the A/D module. The ADCON1 register, shown in Figure 8-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be a voltage reference) or as digital I/O.

R/W-0	R/W-0 R/W-0 R/W-0 R/W-0 U-0 R/W-0								
ADCS1 bit7	ADCS0 CHS2 CHS1 CHS0 GO/DONE — ADON R = Readable bit bit0 bit0 U = Writable bit U = Unimplemented bit, read as '0' -n = Value at POR Reset								
bit 7-6:	ADCS1:ADCS0: A/D Conversion Clock Select bits 00 = Fosc/2 01 = Fosc/8 10 = Fosc/32 11 = FRC (clock derived from the internal ADC RC oscillator)								
bit 5-3:	bit 5-3: CHS2:CHS0 : Analog Channel Select bits 000 = channel 0, (RA0/AN0) 001 = channel 1, (RA1/AN1) 010 = channel 2, (RA2/AN2) 011 = channel 3, (RA3/AN3) 1xx = reserved, do not use								
bit 2:	GO/DONE: A/D Conversion Status bit								
	<u>If ADON = 1</u> 1 = A/D conversion in progress (setting this bit starts the A/D conversion) 0 = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conversion is complete)								
bit 1:	Unimplemented: Read as '0'								
bit 0:	ADON: A/D On bit 1 = A/D converter module is operating 0 = A/D converter module is shutoff and consumes no operating current								

FIGURE 8-1: ADCON0 REGISTER (ADDRESS 1Fh)

8.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 9.5TAD per 8-bit conversion. The source of the A/D conversion clock is software selectable. The four possible options for TAD are:

- 2Tosc
- 8Tosc
- 32Tosc
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 $\mu s.$

Table 8-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

8.3 Configuring Analog Port Pins

The ADCON1 and TRISA registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

- Note 1: When reading the port register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.
 - 2: Analog levels on any pin that is defined as a digital input (including the AN3:AN0 pins), may cause the input buffer to consume current that is out of the devices specification.

TABLE 8-1: TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock	Source (TAD)	Device Frequency					
Operation	ADCS1:ADCS0	20 MHz	5 MHz	1.25 MHz	333.33 kHz		
2Tosc	00	100 ns ⁽²⁾	400 ns ⁽²⁾	1.6 μs	6 µs		
8Tosc	01	400 ns ⁽²⁾	1.6 μs	6.4 μs	24 μs ⁽³⁾		
32Tosc	10	1.6 μs	6.4 μs	25.6 μs ⁽³⁾	96 μs ⁽³⁾		
RC ⁽⁵⁾	11	2-6 μs ^(1,4)	2-6 μs ^(1,4)	2-6 μs ^(1,4)	2-6 μs ⁽¹⁾		

Legend: Shaded cells are outside of recommended range.

Note 1: The RC source has a typical TAD time of 4 $\mu s.$

- **2:** These values violate the minimum required TAD time.
- **3:** For faster conversion times, the selection of another clock source is recommended.
- 4: When device frequency is greater than 1 MHz, the RC A/D conversion clock source is recommended for Sleep operation only.

5: For extended voltage devices (LC), please refer to Electrical Specifications section.

9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

The PIC16CXXX can be operated in four different Oscillator modes. The user can program two Configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low-Power Crystal
- XT Crystal/Resonator
- HS High-Speed Crystal/Resonator
- RC Resistor/Capacitor

9.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 9-2). The PIC16CXXX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/ CLKIN pin (Figure 9-3).

FIGURE 9-2:	CRYSTAL/CERAMIC
	RESONATOR OPERATION
	(HS, XT OR LP
	OSC CONFIGURATION)



FIGURE 9-3: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC



TABLE 9-1: CERAMIC RESONATORS

Ranges Tested:

Mode	Freq	OSC1	OSC2				
XT	455 kHz	68-100 pF	68-100 pF				
	2.0 MHz	15-68 pF	15-68 pF				
	4.0 MHz	15-68 pF	15-68 pF				
HS	8.0 MHz	10-68 pF	10-68 pF				
	16.0 MHz	10-22 pF	10-22 pF				
These values are for design guidance only. See							
not	es at bottom of	page.					

TABLE 9-2:CAPACITOR SELECTION FOR
CRYSTAL OSCILLATOR

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2						
LP	32 kHz	33 pF	33 pF						
	200 kHz	15 pF	15 pF						
XT	200 kHz	47-68 pF	47-68 pF						
	1 MHz	15 pF	15 pF						
	4 MHz	15 pF	15 pF						
HS	4 MHz	15 pF	15 pF						
	8 MHz	15-33 pF	15-33 pF						
	20 MHz	15-33 pF	15-33 pF						
These notes a	These values are for design guidance only. See notes at bottom of page								

Note 1:	Recommended values of C1 and C2 are
	identical to the ranges tested (Table 9-1).

- 2: Higher capacitance increases the stability of the oscillator, but also increases the start-up time.
- 3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.
- 4: Rs may be required in HS mode, as well as XT mode to avoid overdriving crystals with low drive level specification.

9.9 Power Control/Status Register (PCON)

The Power Control/Status Register, PCON has two bits.

Bit 0 is Brown-out Reset Status bit, $\overline{\text{BOR}}$. If the BODEN Configuration bit is set, $\overline{\text{BOR}}$ is '1' on Power-on Reset. If the BODEN Configuration bit is clear, $\overline{\text{BOR}}$ is unknown on Power-on Reset. The BOR Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (the BODEN Configuration bit is clear). BOR must then be set by the user and checked on subsequent Resets to see if it is clear, indicating a brown-out has occurred.

Bit 1 is $\overrightarrow{\text{POR}}$ (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 9-3:TIME-OUT IN VARIOUS SITUATIONS

Occillator Configuration	Power	-up	Brown out	Wake-up from		
	PWRTE = 0	PWRTE = 1	Brown-out	Sleep		
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	72 ms + 1024Tosc	1024Tosc		
RC	72 ms	—	72 ms	—		

TABLE 9-4: STATUS BITS AND THEIR SIGNIFICANCE

POR	BOR	ТО	PD	
0	x	1	1	Power-on Reset
0	x	0	x	Illegal, TO is set on POR
0	x	x	0	Illegal, PD is set on POR
1	0	1	1	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	MCLR Reset during normal operation
1	1	1	0	MCLR Reset during Sleep or interrupt wake-up from Sleep

TABLE 9-5: RESET CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	0x
MCLR Reset during normal operation	000h	000u uuuu	uu
MCLR Reset during Sleep	000h	0001 Ouuu	uu
WDT Reset	000h	0000 luuu	uu
WDT Wake-up	PC + 1	uuu0 Ouuu	uu
Brown-out Reset	000h	0001 luuu	u0
Interrupt wake-up from Sleep	PC + 1 ⁽¹⁾	uuul Ouuu	uu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

9.10 Interrupts

The PIC16C712/716 devices have up to 7 sources of interrupt. The Interrupt Control Register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note:	Individual interrupt flag bits are set regard-
	less of the status of their corresponding
	mask bit or the GIE bit.

A Global Interrupt Enable bit, GIE (INTCON<7>) enables (if set) all unmasked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set, regardless of the status of the GIE bit. The GIE bit is cleared on Reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine, as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the Special Function Registers, PIR1 and PIR2. The corresponding interrupt enable bits are contained in Special Function Registers, PIE1 and PIE2, and the peripheral interrupt enable bit is contained in Special Function Register, INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs. The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set, regardless of the status of their corresponding mask bit or the GIE bit.



FIGURE 9-14: INTERRUPT LOGIC

9.12 Watchdog Timer (WDT)

The Watchdog Timer is as a free running, on-chip, RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run, even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device have been stopped, for example, by execution of a SLEEP instruction.

During normal operation, a WDT Time-out generates a device Reset (Watchdog Timer Reset). If the device is in Sleep mode, a WDT Time-out causes the device to wake-up and continue with normal operation (Watchdog Timer Wake-up). The TO bit in the STATUS register will be cleared upon a Watchdog Timer Time-out.

The WDT can be permanently disabled by clearing Configuration bit WDTE (**Section 9.1 "Configuration Bits**").

WDT time-out period values may be found in the Electrical Specifications section under TwDT (parameter #31). Values for the WDT prescaler (actually a postscaler, but shared with the Timer0 prescaler) may be assigned using the OPTION_REG register.

Note: The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device Reset condition.

Note: When a CLRWDT instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared, but the prescaler assignment is not changed.

FIGURE 9-15: WATCHDOG TIMER BLOCK DIAGRAM



FIGURE 9-16: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bits 13:8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits	(1)	_	BODEN ⁽¹⁾	CP1	CP0	PWRTE ⁽¹⁾	WDTE	FOSC1	FOSC0
81h	OPTION_REG	N/A	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0

Legend: Shaded cells are not used by the Watchdog Timer. **Note 1:** See Figure 9-1 for operation of these bits.

12.1 DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)

			Standard Operating Conditions (unless otherwise stated)							
DC CHA	RACTER	ISTICS	Operating	g tempe	rature	0°	$0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial			
						-40°	$C \leq IA \leq +85^{\circ}C$ for industrial			
						-40				
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions			
D001	Vdd	Supply Voltage	4.0	—	5.5	V	XT, RC and LP osc mode			
D001A			4.5	_	5.5	V	HS osc mode			
			VBOR*	—	5.5	V	BOR enabled ⁽⁷⁾			
D002*	Vdr	RAM Data Retention Voltage ⁽¹⁾	—	1.5	_	V				
D003	VPOR	VDD Start Voltage to ensure inter- nal Power-on Reset signal	—	Vss	—	V	See section on Power-on Reset for details			
D004*	SVDD	VDD Rise Rate to ensure internal	0.05	—	_	V/ms	PWRT enabled (PWRTE bit clear)			
D004A*		Power-on Reset signal	TBD		—		PWRT disabled (PWRTE bit set)			
D005	VBOR	Brown-out Reset voltage trip point	3.65	_	4.35	V	BODEN bit set			
D010	IDD	Supply Current ^(2,5)	_	0.8	2.5	mA	Fosc = 4 MHz, VDD = 4.0V			
D013			—	4.0	8.0	mA	Fosc = 20 MHz, VDD = 4.0V			
D020	IPD	Power-down Current ^(3,5)		10.5	42	μΑ	VDD = 4.0V, WDT enabled,-40°C to +85°C			
			—	1.5	16	μA	VDD = $4.0V$, WDT disabled, $0^{\circ}C$ to $+70^{\circ}C$			
D021			_	1.5	19	μA	$VDD = 4.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$			
D021B			—	2.5	19	μA	VDD = 4.0V, WD1 disabled,-40°C to +125°C			
		Module Differential Current ⁽⁶⁾								
D022*	ΔIWDT	Watchdog Timer	—	6.0	20	μA	WDTE bit set, VDD = 4.0V			
D022A*	ΔIBOR	Brown-out Reset	_	IBD	200	μA	BODEN bit set, VDD = 5.0V			
1A	Fosc	LP Oscillator Operating Frequency	0		200	KHz	All temperatures			
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures			
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures			
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures			

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,

- MCLR = VDD; WDT enabled/disabled as specified.
- **3:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and Vss.

4: For RC Osc mode, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will operate correctly to this trip point.

12.2 DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)

	Standard Operating Conditions (unless otherwise stated)								
DC CHA	RACTER	ISTICS	Operating	g tempe	rature	$0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial			
						-40°	$C \le TA \le +85^{\circ}C$ for industrial		
Param	Sym.	Characteristic	Min.	Тур†	Max.	Units	Conditions		
NO.									
D001	Vdd	Supply Voltage	2.5	—	5.5	V			
			VBOR*	—	5.5	V	BOR enabled (Note 7)		
D002*	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5		V			
D003	VPOR	VDD Start Voltage to ensure inter-	—	Vss	—	V	See section on Power-on Reset for details		
		nal Power-on Reset signal							
D004*	SVDD	VDD Rise Rate to ensure internal	0.05	—	—	V/ms	PWRT enabled (PWRTE bit clear)		
D004A*		Power-on Reset signal	TBD	—	—		PWRT disabled (PWRTE bit set)		
							See section on Power-on Reset for details		
D005	VBOR	Brown-out Reset	3.65	—	4.35	V	BODEN bit set		
		voltage trip point							
D010	IDD	Supply Current ^(2,5)	—	2.0	3.8	mA	XT, RC osc modes		
							Fosc = 4 MHz, VDD = 3.0V (Note 4)		
D010A			—	22.5	48	μA	LP osc mode		
							FOSC = 32 kHz, VDD = 3.0V, WDT disabled		
D020	IPD	Power-down Current ^(3,5)	—	7.5	30	μA	VDD = $3.0V$, WDT enabled, $-40^{\circ}C$ to $+85^{\circ}C$		
D021			—	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C		
D021A			—	0.9	5	μA	VDD = $3.0V$, WDT disabled, $-40^{\circ}C$ to $+85^{\circ}C$		
		Module Differential Current ⁽⁶⁾							
D022*	∆Iwdt	Watchdog Timer	—	6.0	20	μA	WDTE bit set, VDD = 4.0V		
D022A*	ΔIBOR	Brown-out Reset	_	TBD	200	μA	BODEN bit set, VDD = 5.0V		
1A	Fosc	LP Oscillator Operating Frequency	0	—	200	KHz	All temperatures		
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures		
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures		
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures		

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

 $\underline{OSC1} = external \text{ square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,}$

 \overline{MCLR} = VDD; WDT enabled/disabled as specified.

3: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and VSS.

4: For RC Osc mode, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will operate correctly to this trip point.

12.4.3 TIMING DIAGRAMS AND SPECIFICATIONS



TABLE 12-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param	Sym.	Characteristic	Min.	Тур†	Max.	Units	Conditions		
No.									
1A	Fosc	External CLKIN Frequency	DC		4	MHz	RC and XT osc modes		
		(Note 1)		(Note 1)		—	4	MHz	HS osc mode (-04)
			DC	—	20	MHz	HS osc mode (-20)		
			DC	—	200	kHz	LP osc mode		
		Oscillator Frequency	DC	_	4	MHz	RC osc mode		
		(Note 1)	0.1	—	4	MHz	XT osc mode		
			4	—	20	MHz	HS osc mode		
			5	—	200	kHz	LP osc mode		
1	Tosc	External CLKIN Period	250	_	—	ns	RC and XT osc modes		
		(Note 1)	250	—	—	ns	HS osc mode (-04)		
			50	—	—	ns	HS osc mode (-20)		
			5	—	—	μs	LP osc mode		
		Oscillator Period	250	_	—	ns	RC osc mode		
		(Note 1)	250	—	10,000	ns	XT osc mode		
			250	—	250	ns	HS osc mode (-04)		
			50	—	250	ns	HS osc mode (-20)		
			5	_	—	μs	LP osc mode		
2	Тсү	Instruction Cycle Time (Note 1)	200		DC	ns	Tcy = 4/Fosc		
3*	TosL,	External Clock in (OSC1) High or	100	_	—	ns	XT oscillator		
	TosH	Low Time	2.5	—	—	μS	LP oscillator		
			15		—	ns	HS oscillator		
4*	TosR,	External Clock in (OSC1) Rise or	_	_	25	ns	XT oscillator		
	TosF	Fall Time	—	—	50	ns	LP oscillator		
			—	—	15	ns	HS oscillator		

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin.

When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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TABLE 12-3: CLKOUT AND I/O TIMING REQUIREMENTS

Param No.	Sym.	Characteristic		Min.	Тур†	Max.	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		_	75	200	ns	Note 1
11*	TosH2ckH	OSC1; to CLKOUT;		-	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		_	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT Ø to Port out valid		—	_	0.5Tcy + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT {	Tosc + 200	_	—	ns	Note 1	
16*	TckH2iol	Port in hold after CLKOUT	0		—	ns	Note 1	
17*	TosH2ioV	OSC1¦ (Q1 cycle) to Port out vali	d	—	50	150	ns	
18*	TosH2iol	OSC1¦ (Q2 cycle) to Port input	Standard	100	_	—	ns	
18A*		invalid (I/O in hold time)	Extended (LC)	200		—	ns	
19*	TioV2osH	Port input valid to OSC11 (I/O in s	setup time)	0		—	ns	
20*	TioR	Port output rise time	Standard	—	10	40	ns	
20A*			Extended (LC)	—		80	ns	
21*	TioF	Port output fall time Standard		—	10	40	ns	
21A*		Extended (LC)		—	_	80	ns	
22††*	TINP	INT pin high or low time		TCY	_	—	ns	
23††*	Trbp	RB7:RB4 change INT high or lov	v time	TCY	_	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edge.

Note1: Measurements are taken in RC mode where CLKOUT output is 4 x Tosc.

TABLE 12-7:A/D CONVERTER CHARACTERISTICS:
PIC16C712/716-04 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16C712/716-20 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16LC712/716-04 (COMMERCIAL, INDUSTRIAL)

Param No.	Sym.	Characteristic		Min.	Тур†	Max.	Units	Conditions
A01	NR	Resolution	—	_	8-bits	bit	VREF = VDD = 5.12V, VSS £ VAIN £ VREF	
A02	Eabs	Total Absolute error		-	_	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A03	EIL	Integral linearity error		-	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A04	Edl	Differential linearity erro	or	-	_	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A05	EFS	Full scale error	-	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF	
A06	EOFF	Offset error		-	_	< ± 1	LSb	VREF = VDD = 5.12V, VSS £ VAIN £ VREF
A10	—	Monotonicity		_	guaranteed (Note 3)	_	—	VSS £ VAIN £ VREF
A20	VREF	Reference voltage		2.5V	—	Vdd + 0.3	V	
A25	VAIN	Analog input voltage		Vss - 0.3	—	Vref + 0.3	V	
A30	ZAIN	Recommended impeda analog voltage source	nce of	-	_	10.0	kΩ	
A40	IAD	A/D conversion cur-	Standard	—	180	_	μΑ	Average current consump-
		rent (VDD)	Extended (LC)	—	90	_	μΑ	tion when A/D is on. (Note 1)
A50	IREF	VREF input current (Not	e 2)	10	_	1000	μΑ μΑ	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 9.1 "Configuration Bits" . During A/D Conversion
								cycle

2: * These parameters are characterized but not tested.

3: † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current.

The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the Input Voltage, and has no missing codes.